

We claim:

1. A method of coating a wafer, comprising the steps:
 - dispensing a slow-evaporation solvent on the wafer;
 - spinning the wafer until the solvent is distributed across the wafer surface;
 - dispensing a photoresist solution on the wafer having solvent on its surface; and
 - spinning the wafer until the photoresist is distributed across the wafer surface.
2. The method of claim 1 wherein the step of dispensing a slow-evaporation solvent comprises dispensing a diacetone alcohol solvent on the wafer;
3. The method of claim 1 wherein the step of dispensing a slow-evaporation solvent comprises:
 - positioning a nozzle to dispense the solvent in the middle of the wafer;
 - controlling the nozzle with a solenoid; and
 - causing the nozzle to dispense the solvent by signaling the solenoid.
4. A method of coating a wafer, comprising the steps:
 - incorporating an additional nozzle into a wafer processing machine;
 - positioning the additional nozzle such that it is directed at the center of a wafer held in the wafer processing machine;
 - causing the nozzle to dispense solvent on the wafer by triggering a solenoid;
 - spinning the wafer until the solvent is distributed across the wafer surface;
 - dispensing a photoresist solution on the wafer having solvent on its surface; and

spinning the wafer until the photoresist is distributed across the wafer surface.

5. The method of claim 4 wherein the solvent comprises diacetone alcohol.

6. An apparatus for coating a wafer, comprising:
three or more solenoids, including a first, second and third solenoid; and
a solvent dispense head connected to the three or more solenoids, the
solvent dispense head comprising three or more nozzles, including a first
second and third nozzle, wherein:

the first nozzle is activated by the first solenoid;
the second nozzle is activated by the second solenoid; and
the third nozzle is activated by the third solenoid.

7. The apparatus of claim 6, further comprising a rotatable base for holding the wafer, the rotatable base positioned relative to the solvent dispense head such that:

the first nozzle is directed at the center of the wafer,
the second nozzle is directed at the top of the wafer, and
the third nozzle is directed at the back of the wafer.

8. An apparatus for coating a wafer, comprising:
a rotatable base for holding the wafer;
a solvent dispense head comprising three or more nozzles, including a
first second and third nozzle, the solvent dispense head positioned relative to
the rotatable base such that:

the first nozzle is directed at the center of the wafer,
the second nozzle is directed at the top of the wafer, and
the third nozzle is directed at the back of the wafer; and

three or more solenoids, including a first, second and third solenoid, the three or more solenoids connected to the solvent dispense head such that the first nozzle is activated by the first solenoid, the second nozzle is activated by the second solenoid, and the third nozzle is activated by the third solenoid.

9. An apparatus for coating a wafer, comprising:
a rotatable base for mounting the wafer;
a first nozzle for dispensing solvent on center of the mounted wafer; and
a first solenoid connected to the first nozzle.

10. The apparatus of claim 9, further comprising:
a fixed solvent dispense head wherein:
the first nozzle is incorporated in the solvent dispense head; and
the dispense head is positioned relative to the rotatable base such that the first nozzle is directed at the center of the mounted wafer.

11. A system for coating a wafer, comprising:
a bulk solvent container;
a low pressure canister connected to the bulk solvent container; and
a track coating unit connected to the low pressure canister, the track coating unit comprising:
a solvent dispense head having three or more nozzles; and
a rotatable base for mounting the wafer.

12. The system of claim 11 wherein the bulk solvent container contains a solvent comprising aliphatic ester and diacetone alcohol.